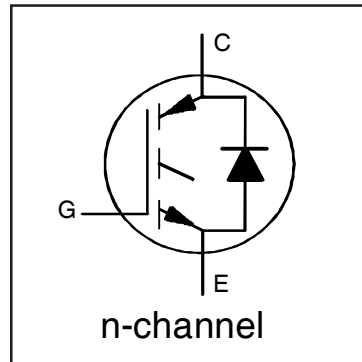


IRGI4062DPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

Features

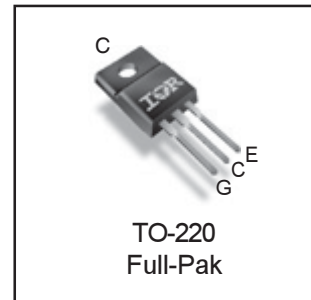
- Low $V_{CE(ON)}$ Trench IGBT Technology
- Low switching losses
- 5 μ S short circuit SOA
- Square RBSOA
- 100% of the parts tested for I_{LM}
- Positive $V_{CE(ON)}$ Temperature co-efficient
- Ultra fast soft Recovery Co-Pak Diode
- Tight parameter distribution
- Lead Free Package



$V_{CES} = 600V$
$I_C = 12A, T_C = 100^\circ C$
$t_{SC} \geq 5\mu s, T_{J(max)} = 150^\circ C$
$V_{CE(on)} \text{ typ.} = 1.34V$

Benefits

- High Efficiency in a wide range of applications
- Suitable for a wide range of switching frequencies due to Low $V_{CE(ON)}$ and Low Switching losses
- Rugged transient Performance for increased reliability
- Excellent Current sharing in parallel operation
- Low EMI



G	C	E
Gate	Collector	Emitter

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	22	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	12	
I_{CM}	Pulse Collector Current	44	
I_{LM}	Clamped Inductive Load Current ①	44	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	22	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	12	
I_{FM}	Diode Maximum Forward Current ②	44	
V_{GE}	Continuous Gate-to-Emitter Voltage	± 20	
	Transient Gate-to-Emitter Voltage	± 30	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	48	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	19	
T_J	Operating Junction and	-55 to +150	$^\circ C$
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1 N-m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance Junction-to-Case-(each IGBT)	—	—	2.6	$^\circ C/W$
$R_{\theta JC}$ (Diode)	Thermal Resistance Junction-to-Case-(each Diode)	—	—	4.2	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface)	—	0.50	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (typical socket mount)	—	—	65	

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig
V _{(BR)CES}	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V _{GE} = 0V, I _C = 100μA ③	CT6
ΔV _{(BR)CES} /ΔT _J	Temperature Coeff. of Breakdown Voltage	—	0.80	—	V/°C	V _{GE} = 0V, I _C = 1mA (-55°C-150°C)	CT6
V _{CE(on)}	Collector-to-Emitter Saturation Voltage	—	1.34	1.58	V	I _C = 12A, V _{GE} = 15V, T _J = 25°C	5,6,7
		—	1.49	—		I _C = 12A, V _{GE} = 15V, T _J = 125°C	9,10,11
		—	1.54	—		I _C = 12A, V _{GE} = 15V, T _J = 150°C	
V _{GE(th)}	Gate Threshold Voltage	4.0	—	6.5	V	V _{CE} = V _{GE} , I _C = 700μA	9, 10,
ΔV _{GE(th)} /ΔT _J	Threshold Voltage temp. coefficient	—	-14	—	mV/°C	V _{CE} = V _{GE} , I _C = 1.0mA (-55°C - 150°C)	11, 12
g _{fe}	Forward Transconductance	—	13	—	S	V _{CE} = 50V, I _C = 12A, PW = 80μs	
I _{CES}	Collector-to-Emitter Leakage Current	—	—	25	μA	V _{GE} = 0V, V _{CE} = 600V	
		—	—	250		V _{GE} = 0V, V _{CE} = 600V, T _J = 150°C	
V _{FM}	Diode Forward Voltage Drop	—	1.70	2.05	V	I _F = 12A	8
		—	1.22	—		I _F = 12A, T _J = 150°C	
I _{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V _{GE} = ±20V	

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig
Q _g	Total Gate Charge (turn-on)	—	48	72	nC	I _C = 12A	24
Q _{ge}	Gate-to-Emitter Charge (turn-on)	—	13	20		V _{GE} = 15V	CT1
Q _{gc}	Gate-to-Collector Charge (turn-on)	—	18	27		V _{CC} = 400V	
E _{on}	Turn-On Switching Loss	—	31	131	μJ	I _C = 12A, V _{CC} = 400V, V _{GE} = 15V	CT4
E _{off}	Turn-Off Switching Loss	—	183	283		R _G = 10Ω, L = 0.13mH, T _J = 25°C	
E _{total}	Total Switching Loss	—	214	414		Energy losses include tail & diode reverse recovery	
t _{d(on)}	Turn-On delay time	—	41	53	ns	I _C = 12A, V _{CC} = 400V, V _{GE} = 15V	CT4
t _r	Rise time	—	18	25		R _G = 10Ω, L = 0.13mH, T _J = 25°C	
t _{d(off)}	Turn-Off delay time	—	100	110			
t _f	Fall time	—	27	35			
E _{on}	Turn-On Switching Loss	—	130	—	μJ	I _C = 12A, V _{CC} = 400V, V _{GE} = 15V	13, 15
E _{off}	Turn-Off Switching Loss	—	275	—		R _G = 10Ω, L = 0.13mH, T _J = 150°C ③	CT4
E _{total}	Total Switching Loss	—	405	—		Energy losses include tail & diode reverse recovery	WF1, WF2
t _{d(on)}	Turn-On delay time	—	39	—	ns	I _C = 12A, V _{CC} = 400V, V _{GE} = 15V	14, 16
t _r	Rise time	—	16	—		R _G = 10Ω, L = 0.13mH	CT4
t _{d(off)}	Turn-Off delay time	—	119	—		T _J = 150°C	WF1
t _f	Fall time	—	39	—			WF2
C _{ies}	Input Capacitance	—	1528	—	pF	V _{GE} = 0V	23
C _{oes}	Output Capacitance	—	126	—		V _{CC} = 30V	
C _{res}	Reverse Transfer Capacitance	—	39	—		f = 1.0Mhz	
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T _J = 150°C, I _C = 44A V _{CC} = 480V, V _p = 600V R _G = 100Ω, V _{GE} = +15V to 0V	4 CT2
SCSOA	Short Circuit Safe Operating Area	5	—	—	μs	V _{CC} = 400V, V _p = 600V R _G = 100Ω, V _{GE} = +15V to 0V	22, CT3 WF4
E _{rec}	Reverse Recovery Energy of the Diode	—	362	—	μJ	T _J = 150°C	17, 18, 19
t _{rr}	Diode Reverse Recovery Time	—	56	—	ns	V _{CC} = 400V, I _F = 12A	20, 21
I _{rr}	Peak Reverse Recovery Current	—	30	—	A	V _{GE} = 15V, R _G = 10Ω, L = 0.13mH	WF3

Notes:

- ① V_{CC} = 80% (V_{CES}), V_{GE} = 15V, L = 28μH, R_G = 10Ω.
- ② Pulse width limited by max. junction temperature.
- ③ Refer to AN-1086 for guidelines for measuring V_{(BR)CES} safely.

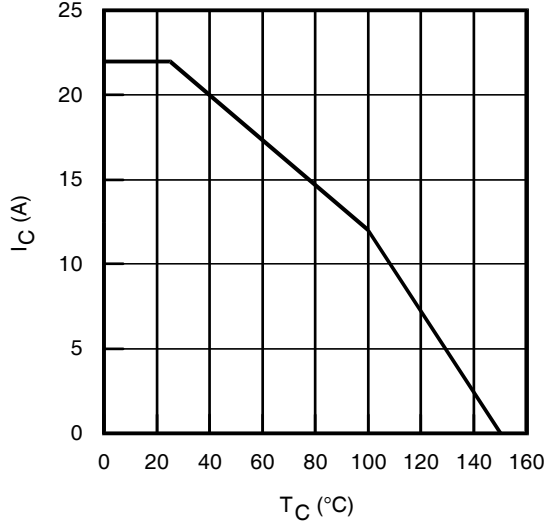


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

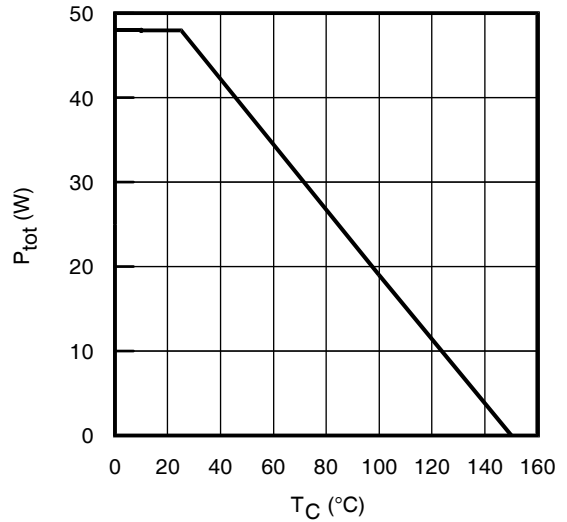


Fig. 2 - Power Dissipation vs. Case Temperature

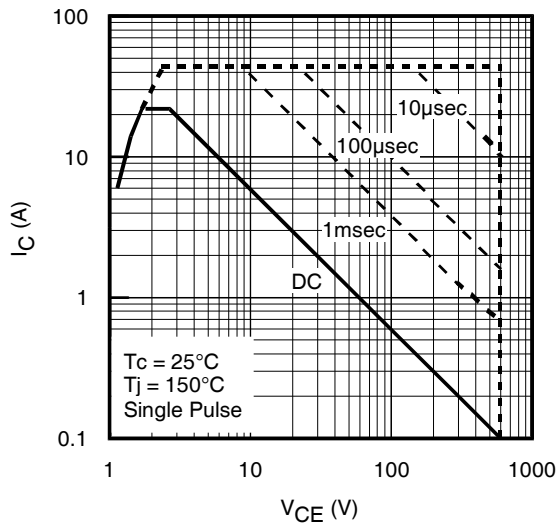


Fig. 3 - Forward SOA

$T_C = 25^{\circ}C$, $T_J \leq 150^{\circ}C$; $V_{GE} = 15V$

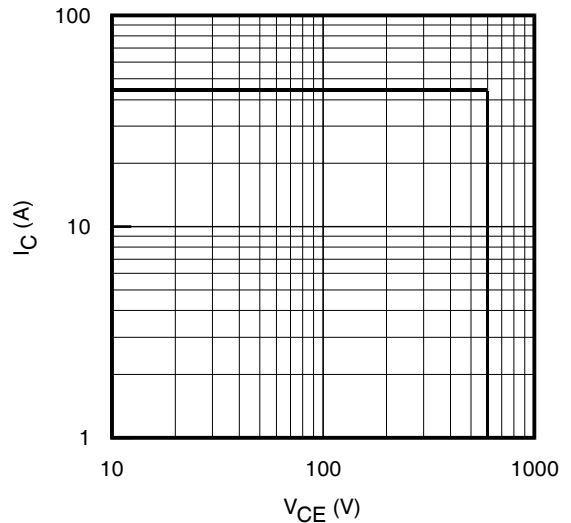


Fig. 4 - Reverse Bias SOA

$T_J = 150^{\circ}C$; $V_{GE} = 15V$

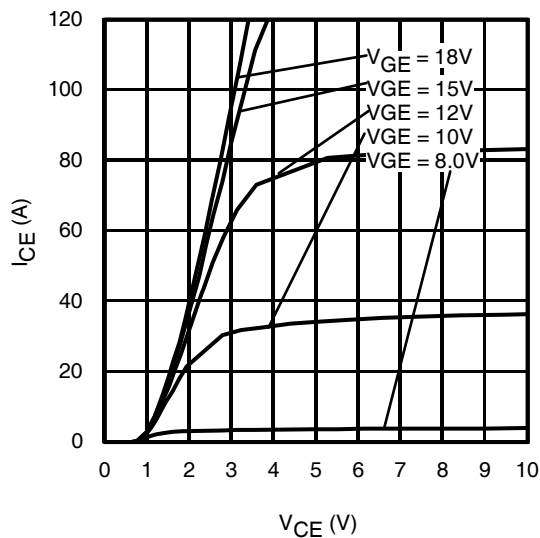


Fig. 5 - Typ. IGBT Output Characteristics
 $T_J = -40^{\circ}C$; $t_p = 80\mu s$

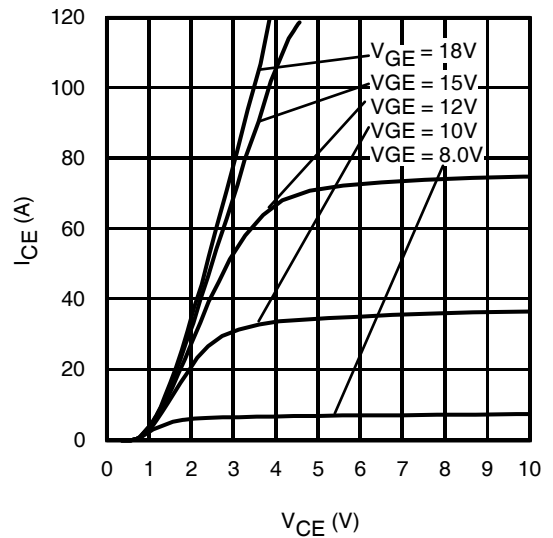


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = 25^{\circ}C$; $t_p = 80\mu s$

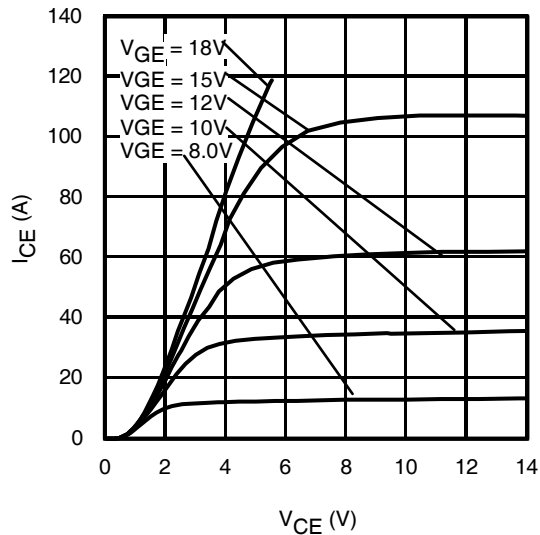


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 150^\circ\text{C}$; $t_p = 80\mu\text{s}$

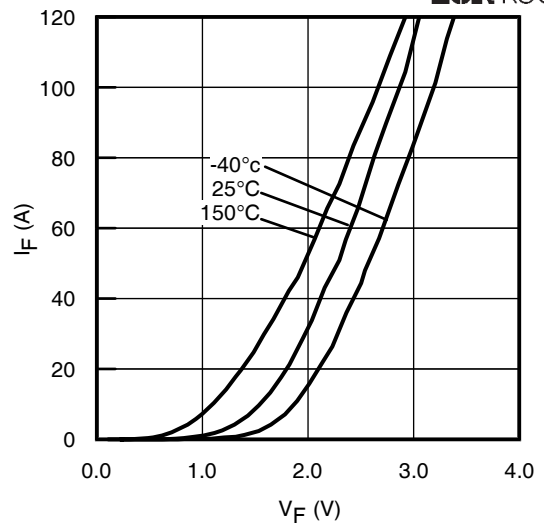


Fig. 8 - Typ. Diode Forward Characteristics
 $t_p = 80\mu\text{s}$

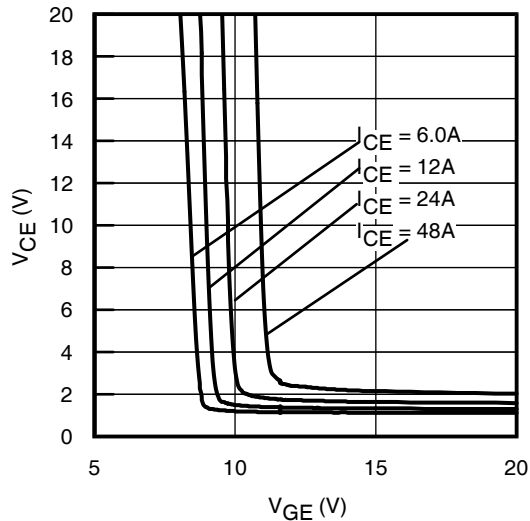


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

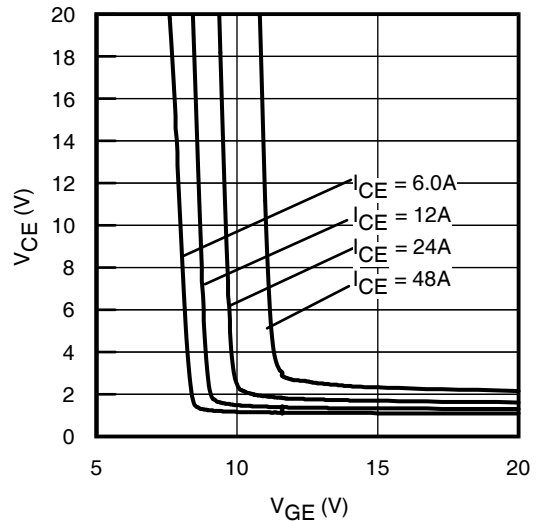


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

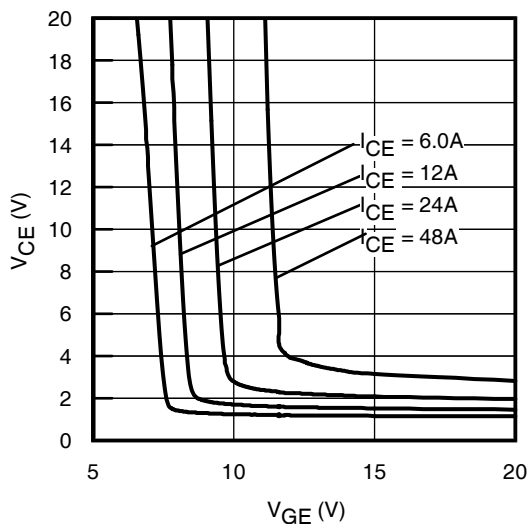


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 150^\circ\text{C}$

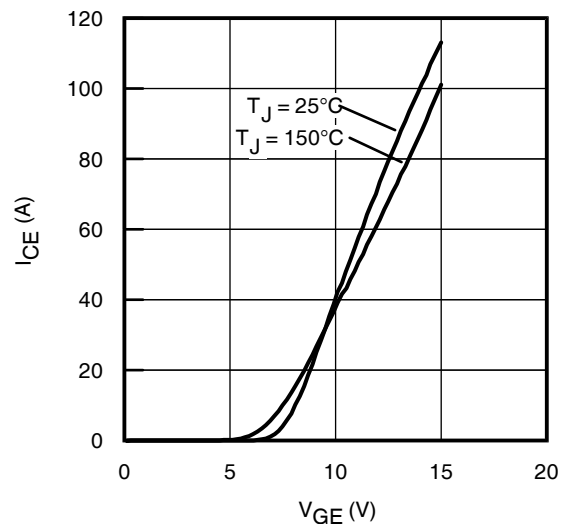


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}$; $t_p = 10\mu\text{s}$

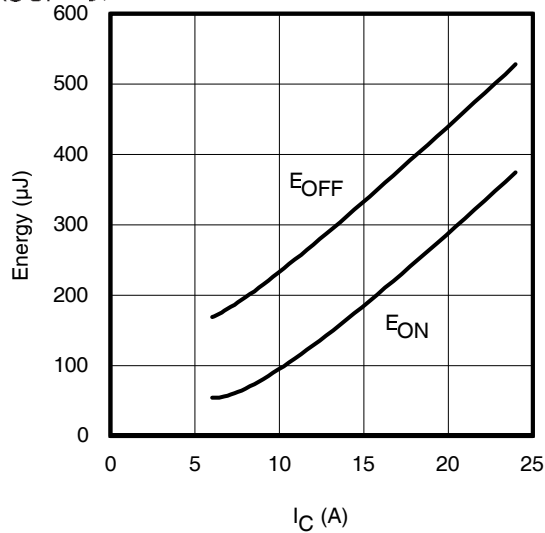


Fig. 13 - Typ. Energy Loss vs. I_C

T_J = 150°C; L = 0.13mH; V_{CE} = 400V, R_G = 10Ω; V_{GE} = 15V

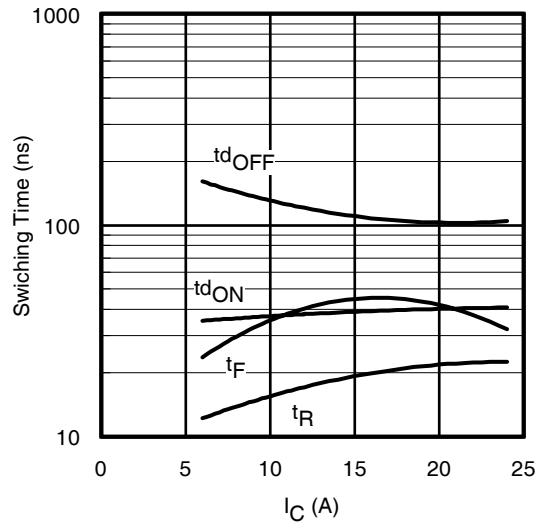


Fig. 14 - Typ. Switching Time vs. I_C

T_J = 150°C; L = 0.13mH; V_{CE} = 400V, R_G = 10Ω; V_{GE} = 15V

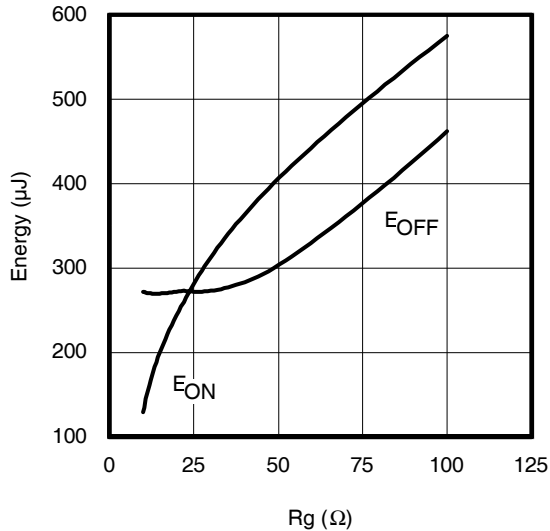


Fig. 15 - Typ. Energy Loss vs. R_G

T_J = 150°C; L = 0.13mH; V_{CE} = 400V, I_{CE} = 12A; V_{GE} = 15V

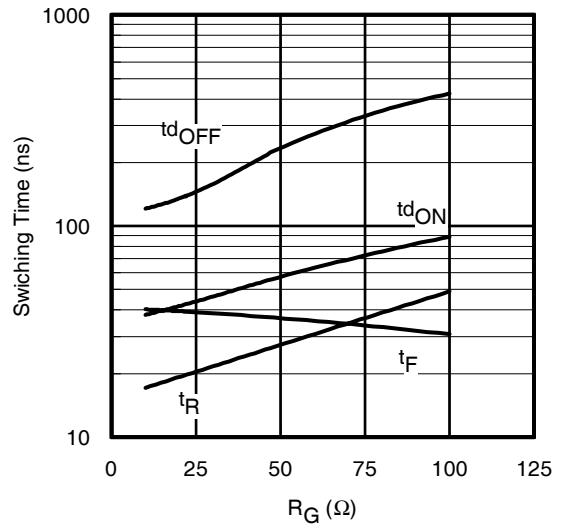


Fig. 16 - Typ. Switching Time vs. R_G

T_J = 150°C; L = 0.13mH; V_{CE} = 400V, I_{CE} = 12A; V_{GE} = 15V

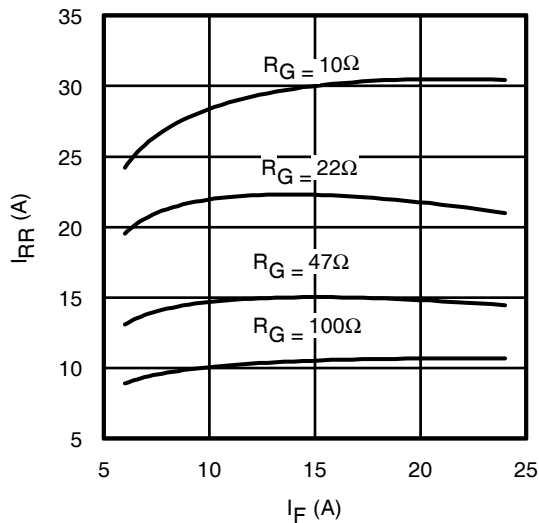


Fig. 17 - Typ. Diode I_{RR} vs. I_F

T_J = 150°C

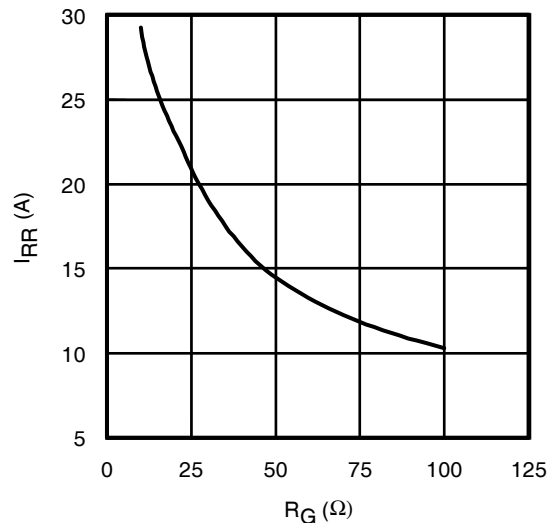


Fig. 18 - Typ. Diode I_{RR} vs. R_G

T_J = 150°C

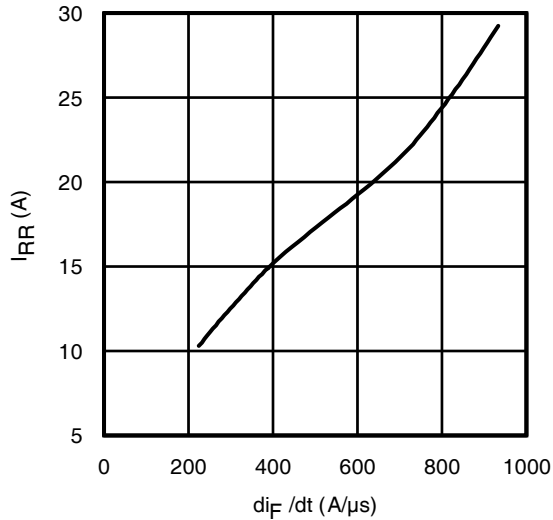


Fig. 19 - Typ. Diode I_{RR} vs. di_F/dt
 $V_{CC} = 400V$; $V_{GE} = 15V$; $I_F = 12A$; $T_J = 150^\circ C$

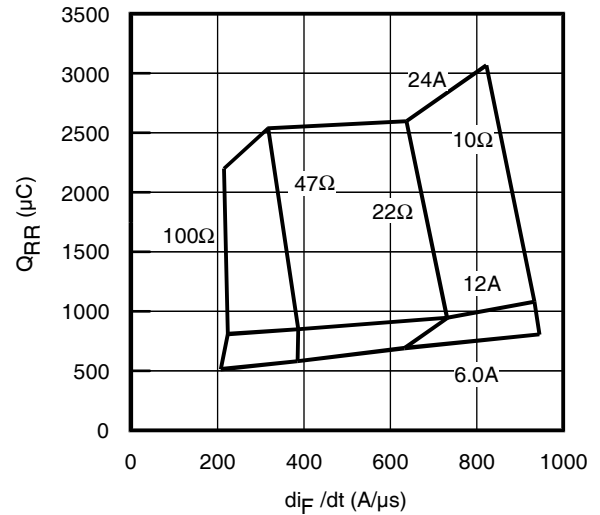


Fig. 20 - Typ. Diode Q_{RR} vs. di_F/dt
 $V_{CC} = 400V$; $V_{GE} = 15V$; $T_J = 150^\circ C$

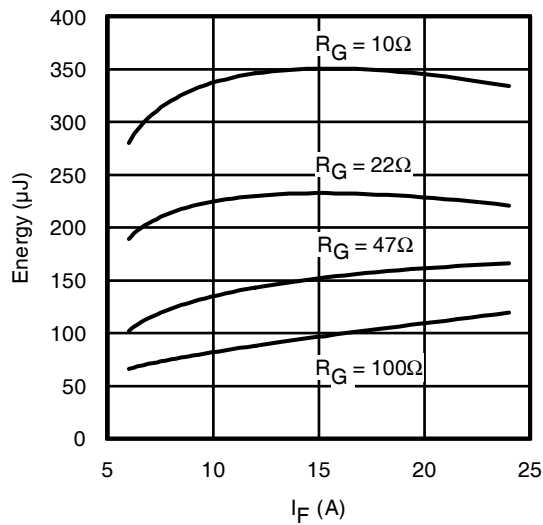


Fig. 21 - Typ. Diode E_{RR} vs. I_F
 $T_J = 150^\circ C$

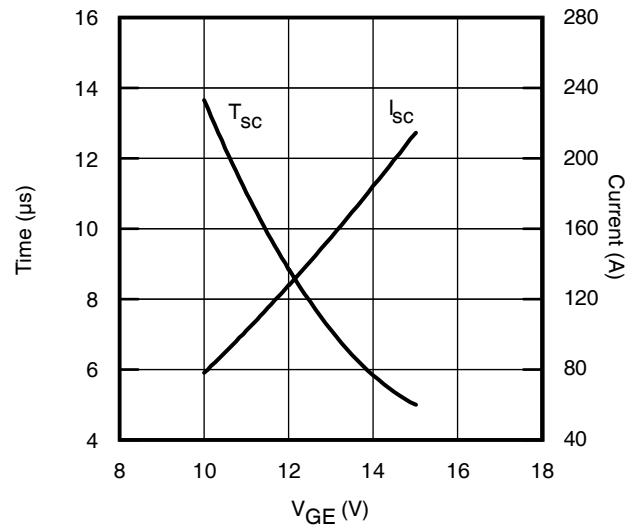


Fig. 22 - V_{GE} vs. Short Circuit Time
 $V_{CC} = 400V$; $T_C = 25^\circ C$

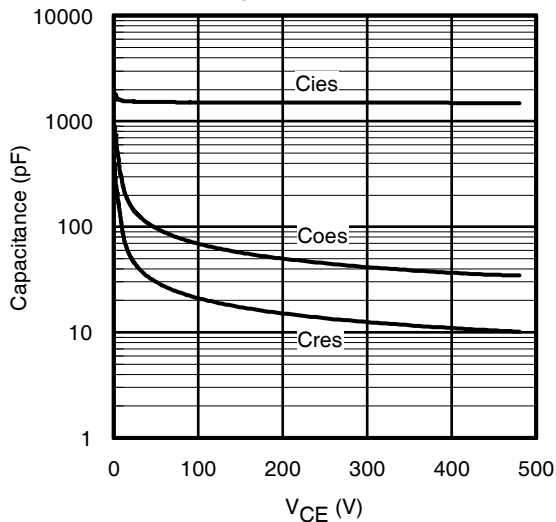


Fig. 23 - Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0V$; $f = 1MHz$

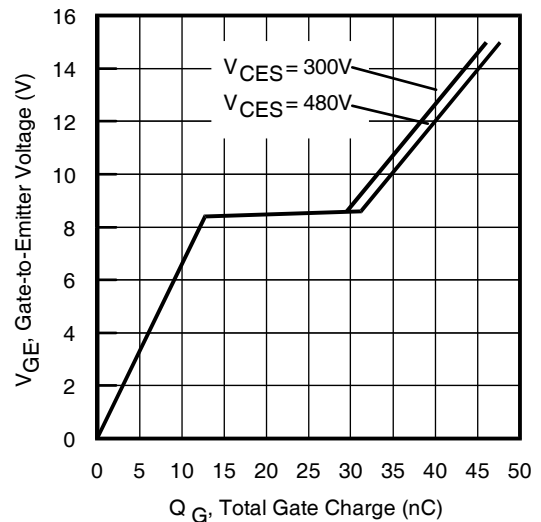


Fig. 24 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 12A$; $L = 1700\mu H$

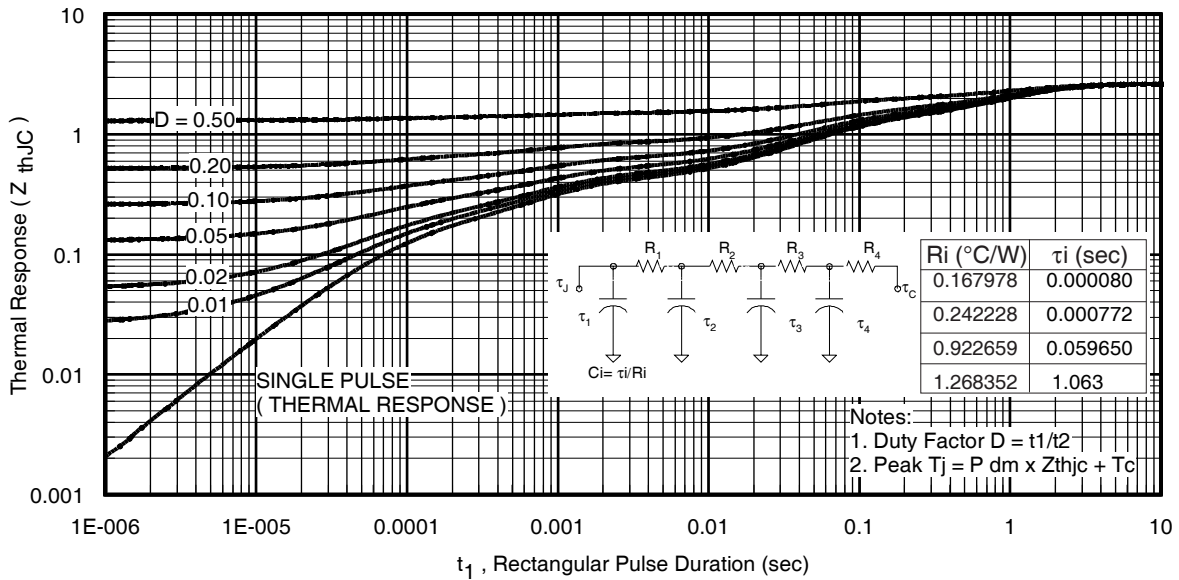


Fig 23. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

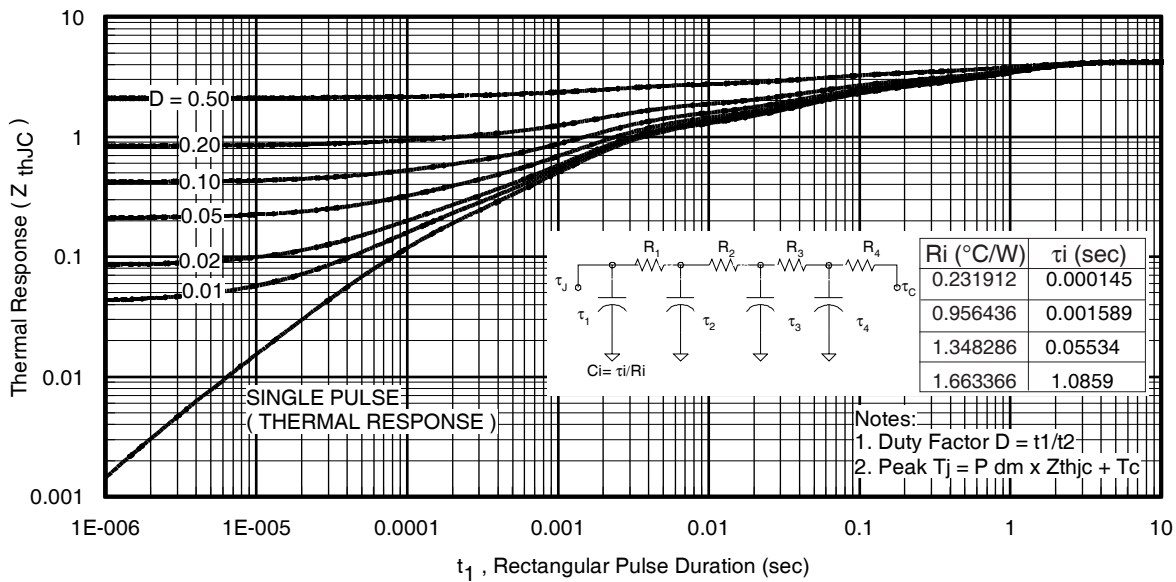


Fig. 24. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

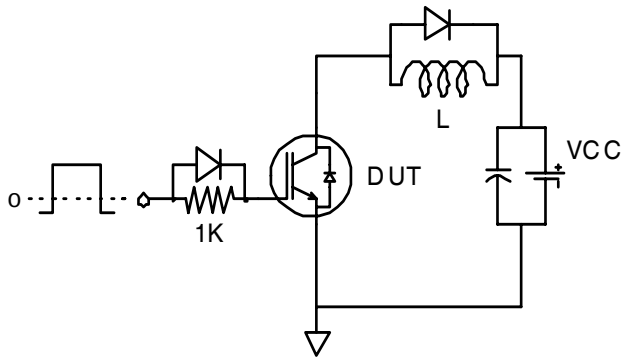


Fig.C.T.1 - Gate Charge Circuit (turn-off)

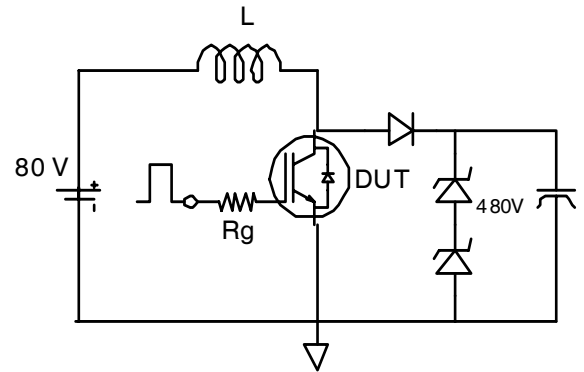


Fig.C.T.2 - RBSOA Circuit

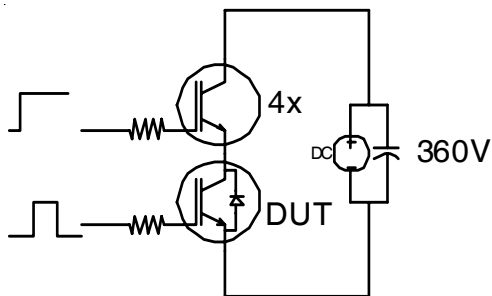


Fig.C.T.3 - S.C. SOA Circuit

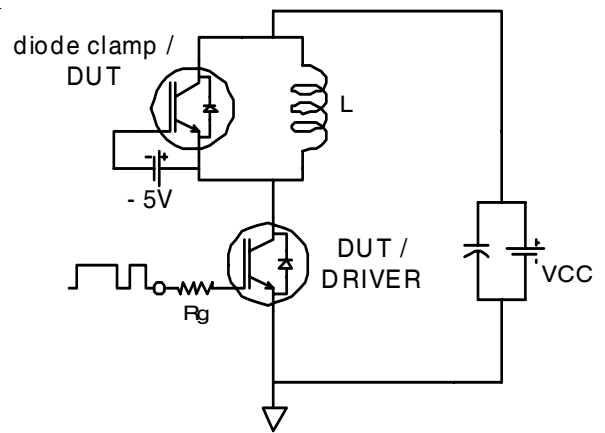


Fig.C.T.4 - Switching Loss Circuit

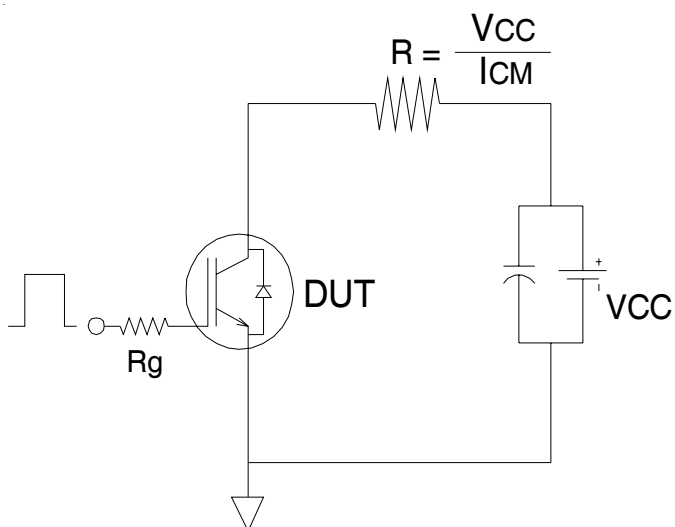


Fig.C.T.5 - Resistive Load Circuit

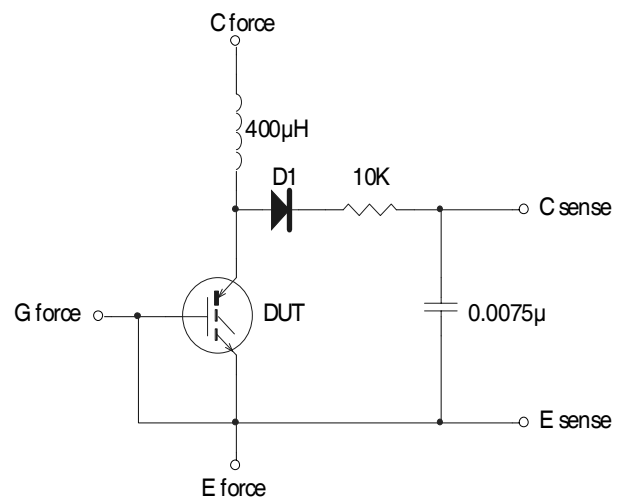


Fig.C.T.6 - BVGES Filter Circuit

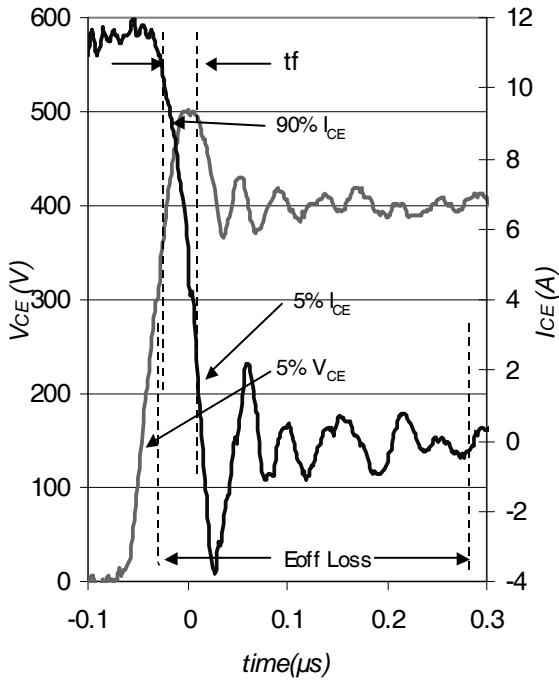


Fig. WF1 - Typ. Turn-off Loss Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

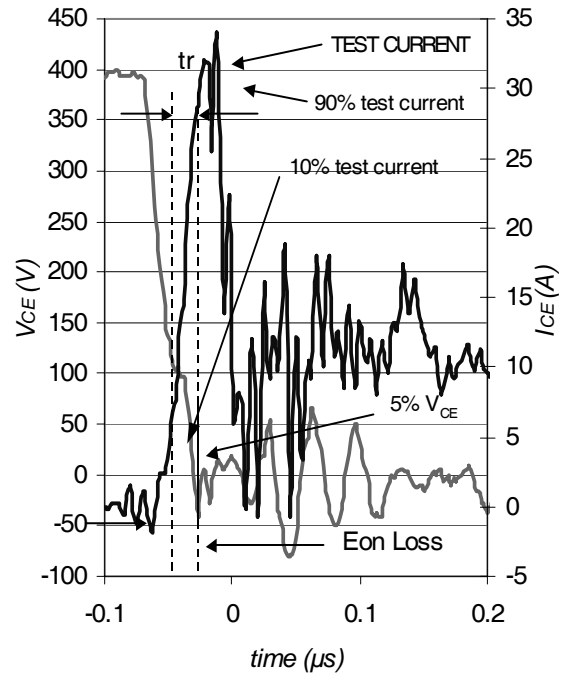


Fig. WF2 - Typ. Turn-on Loss Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

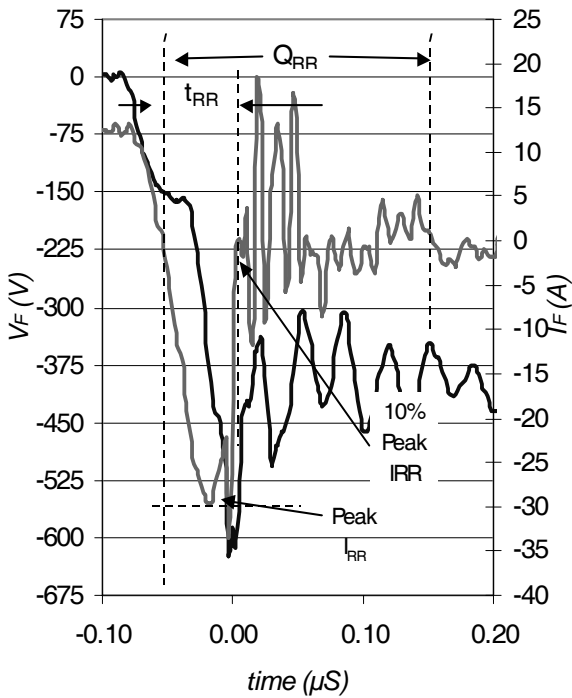


Fig. WF3 - Typ. Diode Recovery Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

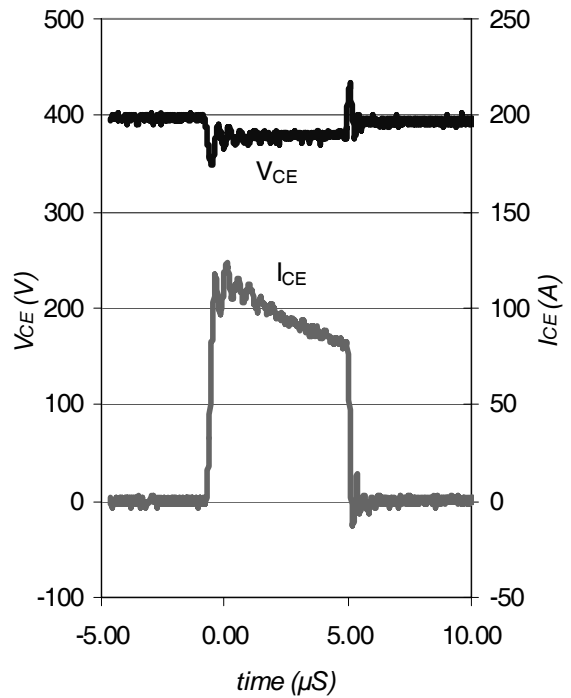
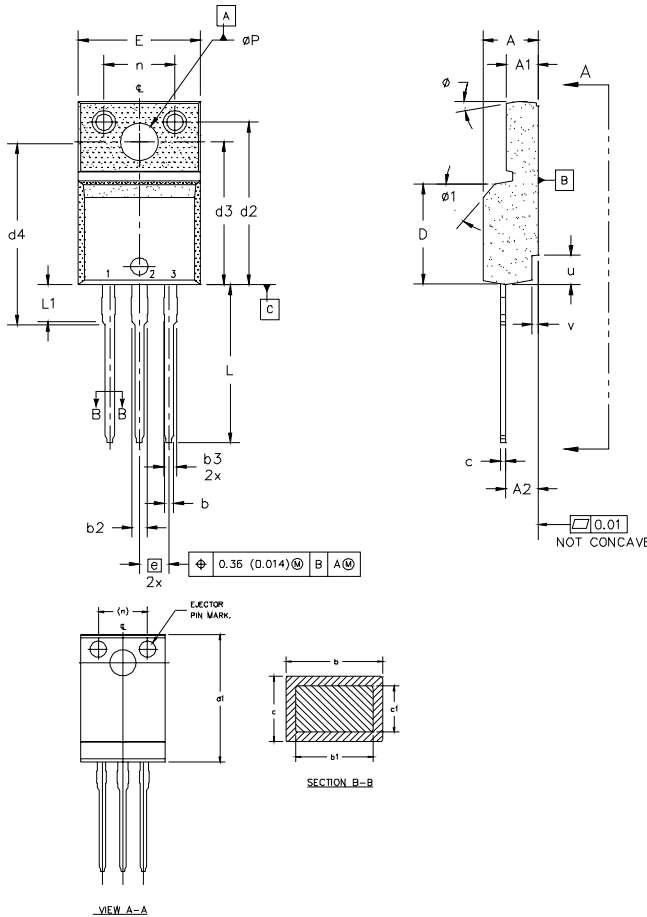


Fig. WF4 - Typ. S.C. Waveform
@ $T_J = 25^\circ\text{C}$ using Fig. CT.3

IRGI4062DPbF

TO-220 Full-Pak Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
- 1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
 - 2.0 DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
 - 3.0 LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
 - 4.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 - 5.0 DIMENSION b1 APPLY TO BASE METAL ONLY.
 - 6.0 STEP OPTIONAL ON PLASTIC BODY DEFINED BY DIMENSIONS u & v.
 - 7.0 CONTROLLING DIMENSION : INCHES.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.57	4.83	0.180	0.190	
A1	2.57	2.83	0.101	0.114	
A2	2.51	2.85	0.099	0.112	
b	0.622	0.89	0.024	0.035	
b1	0.622	0.838	0.024	0.033	5
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
c	0.440	0.629	0.017	0.025	
d	0.440	0.584	0.017	0.023	4
D	8.65	9.80	0.341	0.386	
d1	15.80	16.12	0.622	0.635	
d2	13.97	14.22	0.550	0.560	
d3	12.30	12.92	0.484	0.509	
d4	8.64	9.91	0.340	0.390	
E	10.36	10.63	0.408	0.419	4
e	2.54 BSC		0.100 BSC		
L	13.20	13.73	0.520	0.541	
L1	3.10	3.50	0.122	0.138	3
n	6.05	6.15	0.238	0.242	
phi P	3.05	3.45	0.120	0.136	
u	2.40	2.50	0.094	0.098	6
v	0.40	0.50	0.016	0.020	6
phi	3"	7"	3"	7"	
phi 1		45'		45'	

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE

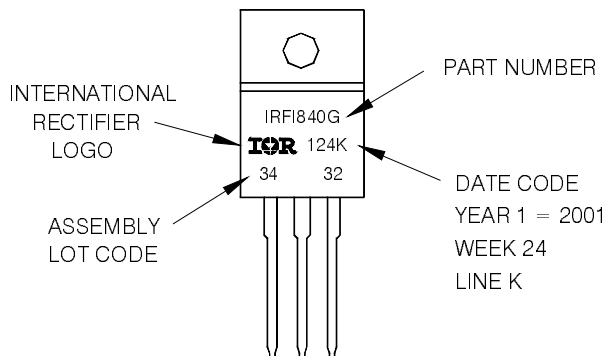
IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER

TO-220 Full-Pak Part Marking Information

EXAMPLE: THIS IS AN IRFI840G
WITH ASSEMBLY
LOT CODE 3432
ASSEMBLED ON WW 24, 2001
IN THE ASSEMBLY LINE "K"

Note: "P" in assembly line position indicates "Lead-Free"



TO-220 Full-Pak package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial market.
Qualification Standards can be found on IR's Web site.